

PRESSURE OVEN

(가압오븐)

INNOVATIVE
& CREATIVE DESIGNER GROUP
WITH PASSION, EFFORTS & IDEA

Welcome to visit us, we will be your best partner for
design of high pressure & high temperature applications.



SINGLE CHAMBER MINI TYPE
(180°C, 16bar)



SINGLE AUTO DOOR CHAMBER TYPE
(200°C, 20bar)



DUAL CHAMBER TYPE
(200°C, 8BAR)



SINGLE CHAMBER TYPE
(200°C, 8bar)

SINGLE CHAMBER TYPE
(200°C, 20bar)

(가압오븐)

개요(Summary)

반도체 패키징 공정 또는 TFT-LCD, PDP, GLASS 등의 LAMINATION 공정에서 접착제(결합제)내부에 존재하는 미세 기포를 제거하는 설비로서, 챔버(압력용기)내부의 가압 및 승온 동작을 수행하며, 정밀한 온도 및 압력 제어를 통해 탈포 작업(De-airation)이 수행되며, 그 결과 안정된 경화 및 밀착성을 높일 수 있는 설비입니다.

용도 → De-airation(void elimination)

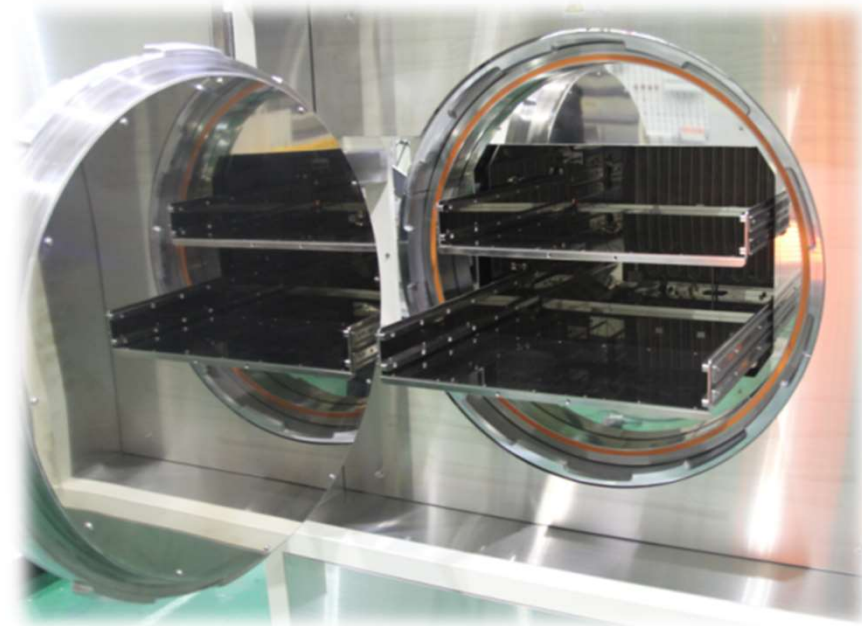
- ★ Wafer Lamination
- ★ Die Bonding
- ★ TC Bonding(Thermo compressing bonding, 열 압착 접합)
- ★ Dispensing / Printing / Potting
- ★ Via Filling
- ★ Capillary underfilling / No flow underfilling
- ★ Reflow
- ★ TFT-LCD, PDP, GLASS Etc.



(가압 오븐)

특징 (Features)

- ★ 빠른 승온, 승압 및 냉각 CYCLE 구현
- 생산효율 증가
- ★ 정밀한 온도 및 압력 제어
- ★ 편리한 적재성 (슬라이드 레일)
- ★ 압력용기 제작 규격에 의한 설계, 제작 및 승인기관의 검사
- ★ 편리한 자동운전 시퀀스
- ★ 다중 안전장치(전기 및 기계적)를 적용한 안전한 디자인
- ★ 신속한 사후관리 서비스



편리한 슬라이드 레일 적재구조 (Mini type은 제외됨.)

일반사양 (General specification)

Max. operation condition	Pressure : 8bar / 20 bar, Temperature : 200 °C
Wet parts material	STS304

* 세부 기술사양은 당사 기술 영업팀과 상의하세요.

GENERAL SPECIFICATION & FEATURES

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Chamber dia.	520mm I.D / 600mm I.D / 650mm I.D / 700mm I.D (other size available)			
Type	Single chamber / Dual chamber (Below I.D650mm, 8bar only)			
Max. operation condition	Pressure : 8bar / 20 bar Temperature : 200 °C			
Equipment Size (approx.) wo/options	700	Chamber I.D(mm)	Type	Dimensions (except the Tower lamp)
		Single 1	Single 2	1600mm (W) x 2300mm (D) x 1745mm (H) 1250mm (W) x 2180mm (D) x 1740mm (H)
	650	Single1	Single 2	1480mm (W) x 2050mm (D) x 1650mm (H) 1200mm (W) x 2050mm (D) x 1650mm (H)
		Dual		1480mm (W) x 2050mm (D) x 2000mm (H)
		600	Single1	Single 2
	Dual		1430mm (W) x 2050mm (D) x 1935mm (H)	
	520		Single1	Single 2
		Dual		1420mm (W) x 2050mm (D) x 1935mm (H)



DUAL CHAMBER TYPE



SINGLE CHAMBER TYPE 1



SINGLE CHAMBER TYPE 2

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Internal working zone (approx.)	Chamber I.D(mm)	Working zone dimensions
	700	490 mm (W) x 560 mm (D) x 366 mm (H) [2단 2열 적재 구조 w/ slide rail]
	650	440 mm (W) x 500 mm (D) x 335 mm (H) [2단 2열 적재 구조 w/ slide rail]
	600	370 mm (W) x 500 mm (D) x 335 mm (H) [2단 2열 적재 구조 w/ slide rail]
	520	327 mm (W) x 245 mm (D) x 310 mm (H) [2단 2열 적재 구조 w/ slide rail]



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Equipment weight (approx.)	Chamber I.D(mm)	Type	Design pressure (kg/cm ²)	Weight (kg)
	700	Single 1	24	1850
			9.9	1500
		Single 2	24	1850
			9.9	1500
	650	Single	24/16	1800
			9.9	1450
		Dual	24/16	2100
			9.9	1890
	600	Single	24/16	1750
9.9			1400	
Dual		16	2120	
		9.9	1900	
520	Single	24/16	1670	
		9.9	1350	
	Dual	16	2000	
		9.9	1790	



* 세부 기술사양은 당사 기술 영업팀과 상의하세요.

모델 체계(MODEL SYSTEM)

PO1 - 700 - 20 - 200 - OPTION

PO1 : Single Pressure oven
PO1A : Single Auto door type
PO2 : Dual Pressure oven
PO3 : Single Mini Pressure oven

Chamber dia.
(mm)

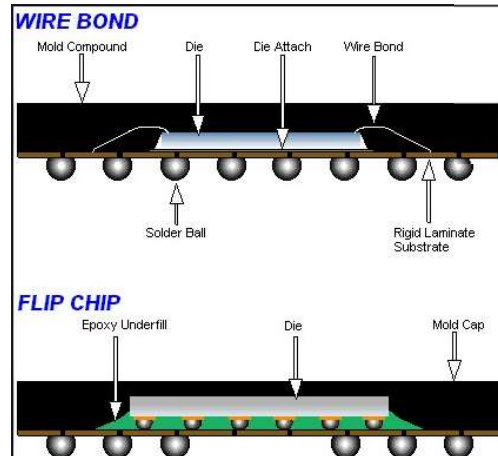
Operation pressure
(kg/cm²)

Operation temp.
(°C)

Options

* Customer 요청 기능

Semiconductor packaging

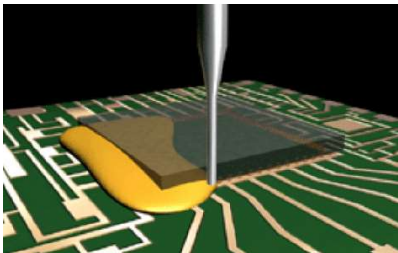


Pressure oven

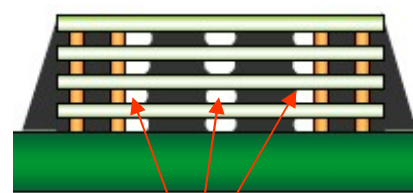


Curing

Underfill



Before cure



Captured void

After cure



No void

APPLICATION EXAMPLE OF PRESSURE OVEN

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